

**A SYSTEM AND METHOD FOR ACHIEVING PLANAR ALIGNMENT  
OF A SUBSTRATE DURING SOLDER BALL MOUNTING FOR USE IN  
SEMICONDUCTOR FABRICATION**

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**ABSTRACT**

A system (10) and method (30) for precisely depositing a solder  
10 compound onto a substrate (18). The system (10) generally includes a receiving  
member (20) having a rotatable portion (21) adapted to receive a planar substrate  
(18), a horizontal member (12) for depositing solder balls (11) on the substrate  
(18), and a contact member (14), located between the receiving member (20) and  
horizontal member (12). The contact member comprises an aligner plate (14)  
15 having a pair of stoppers (15) protruding therefrom. Advantageously, pivotable  
portion (21) of the system (10) establishes the planarity of the substrate (18), with  
respect to the horizontal mount (12) allowing for the solder balls (11) to be  
mounted thereon, preventing the substrate (18) from being slightly misaligned,  
warped, and/or tilted.

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